

# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

|                      |                                                                                                                        |
|----------------------|------------------------------------------------------------------------------------------------------------------------|
| 1.1 Company          |  STMicroelectronics International N.V |
| 1.2 PCN No.          | EMBEDDED PROCESSING/26/16581                                                                                           |
| 1.3 Title of PCN     | HHgrace Wuxi (China) Diffusion site additional source for STM32H74x and STM32H75x listed products.                     |
| 1.4 Product Category | STM32H74x and STM32H75x                                                                                                |
| 1.5 Issue date       | 2026-09-22                                                                                                             |

## 2. PCN Team

|                           |                          |
|---------------------------|--------------------------|
| 2.1 Contact supplier      |                          |
| 2.1.1 Name                | ROBERTSON HEATHER        |
| 2.1.2 Phone               | +1 8475853058            |
| 2.1.3 Email               | heather.robertson@st.com |
| 2.2 Change responsibility |                          |
| 2.2.1 Product Manager     | Patrick AIDOUNE          |
| 2.1.2 Marketing Manager   | Marie TOURNUT            |
| 2.1.3 Quality Manager     | Pascal NARCHE            |

## 3. Change

|              |                                                                                                                                                     |                            |
|--------------|-----------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------|
| 3.1 Category | 3.2 Type of change                                                                                                                                  | 3.3 Manufacturing Location |
| Transfer     | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617) | HHGrace Wuxi (China)       |

## 4. Description of change

|                                                                                       |                                                                                         |                                                                                                                                                                                                           |
|---------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|                                                                                       | Old                                                                                     | New                                                                                                                                                                                                       |
| 4.1 Description                                                                       | Front-end sources for STM32H74x and STM32H75x<br>- ST Crolles (France) CR300 revision V | Front-end sources for STM32H74x and STM32H75x<br>Existing :<br>- ST Crolles (France) CR300 revision V<br>Additional :<br>- HHGrace Wuxi fab7 (China) revision 2<br>- HHGrace Wuxi fab9 (China) revision 3 |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No change on Form, Fit or Function - same datasheet.                                    |                                                                                                                                                                                                           |

## 5. Reason / motivation for change

|                      |                            |
|----------------------|----------------------------|
| 5.1 Motivation       | Second source introduction |
| 5.2 Customer Benefit | CAPACITY INCREASE          |

## 6. Marking of parts / traceability of change

|                 |                                                                                                                         |
|-----------------|-------------------------------------------------------------------------------------------------------------------------|
| 6.1 Description | Change is visible in the marking.<br>Please refer to PCN 16581 Additional information.pdf document for further details. |
|-----------------|-------------------------------------------------------------------------------------------------------------------------|

## 7. Timing / schedule

|                                     |              |
|-------------------------------------|--------------|
| 7.1 Date of qualification results   | 2026-09-08   |
| 7.2 Intended start of delivery      | 2026-10-15   |
| 7.3 Qualification sample available? | Upon Request |

## 8. Qualification / Validation

|                                                    |                                                                                                  |            |            |
|----------------------------------------------------|--------------------------------------------------------------------------------------------------|------------|------------|
| 8.1 Description                                    | 16581 MDG-GPM-RER2304-PCN13841_14224_14728_15910_16068 16581 V6.0-ASE LQ7 LQ20 Cu RER Report.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)                                                                       | Issue Date | 2026-09-22 |

| 9. Attachments (additional documentations)                                                                                                                        |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 16581 Public product.pdf<br>16581 MDG-GPM-RER2304-PCN13841_14224_14728_15910_16068_16581 V6.0-ASE LQ7 LQ20 Cu RER Report.pdf<br>16581 _Additional information.pdf |

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STM32H742VGT6           |                          |
|                         | STM32H742VIT6           |                          |
|                         | STM32H742ZGT6           |                          |
|                         | STM32H743AIH6           |                          |
|                         | STM32H743IGT6           |                          |
|                         | STM32H743IIK6           |                          |
|                         | STM32H743IIT6           |                          |
|                         | STM32H743VGT6           |                          |
|                         | STM32H743VIH6           |                          |
|                         | STM32H743VIT6           |                          |
|                         | STM32H743VIT6TR         |                          |
|                         | STM32H743XIH6           |                          |
|                         | STM32H743XIH6TR         |                          |
|                         | STM32H743ZGT6           |                          |
|                         | STM32H743ZIT6           |                          |
|                         | STM32H743ZIT6TR         |                          |
|                         | STM32H745IIK6           |                          |
|                         | STM32H745IIT6           |                          |
|                         | STM32H745XGH6           |                          |
|                         | STM32H745XIH3           |                          |
|                         | STM32H745XIH6           |                          |
|                         | STM32H745ZIT3           |                          |
|                         | STM32H745ZIT6           |                          |
|                         | STM32H747AIH6           |                          |
|                         | STM32H747IGT6           |                          |
|                         | STM32H747IIT6           |                          |
|                         | STM32H747XIH6           |                          |
|                         | STM32H750IBK6           |                          |
|                         | STM32H750IBK6TR         |                          |
|                         | STM32H750IBT6           |                          |
|                         | STM32H750VBT6           |                          |
|                         | STM32H750VBT6TR         |                          |
|                         | STM32H750XBH6           |                          |
|                         | STM32H750ZBT6           |                          |
|                         | STM32H753AIH6           |                          |
|                         | STM32H753IIK6           |                          |
|                         | STM32H753IIT6           |                          |
|                         | STM32H753VIH6           |                          |
|                         | STM32H753VIT6           |                          |
|                         | STM32H753XIH6           |                          |
|                         | STM32H753XIH6TR         |                          |
|                         | STM32H753ZIT6           |                          |
|                         | STM32H755IIK3           |                          |
|                         | STM32H755IIK6           |                          |

|  |                |  |
|--|----------------|--|
|  | STM32H755IIT3  |  |
|  | STM32H755IIT6  |  |
|  | STM32H755XIH3  |  |
|  | STM32H755XIH6  |  |
|  | STM32H755ZIT3  |  |
|  | STM32H755ZIT6  |  |
|  | STM32H757IIT6  |  |
|  | STM32H757XIH6  |  |
|  | STM32H757XIH6A |  |
|  | STM32H743BGT6  |  |
|  | STM32H743BIT6  |  |
|  | STM32H745BIT6  |  |
|  | STM32H747BIT6  |  |
|  | STM32H753BIT6  |  |
|  | STM32H755BIT3  |  |
|  | STM32H755BIT6  |  |
|  | STM32H757BIT6  |  |

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